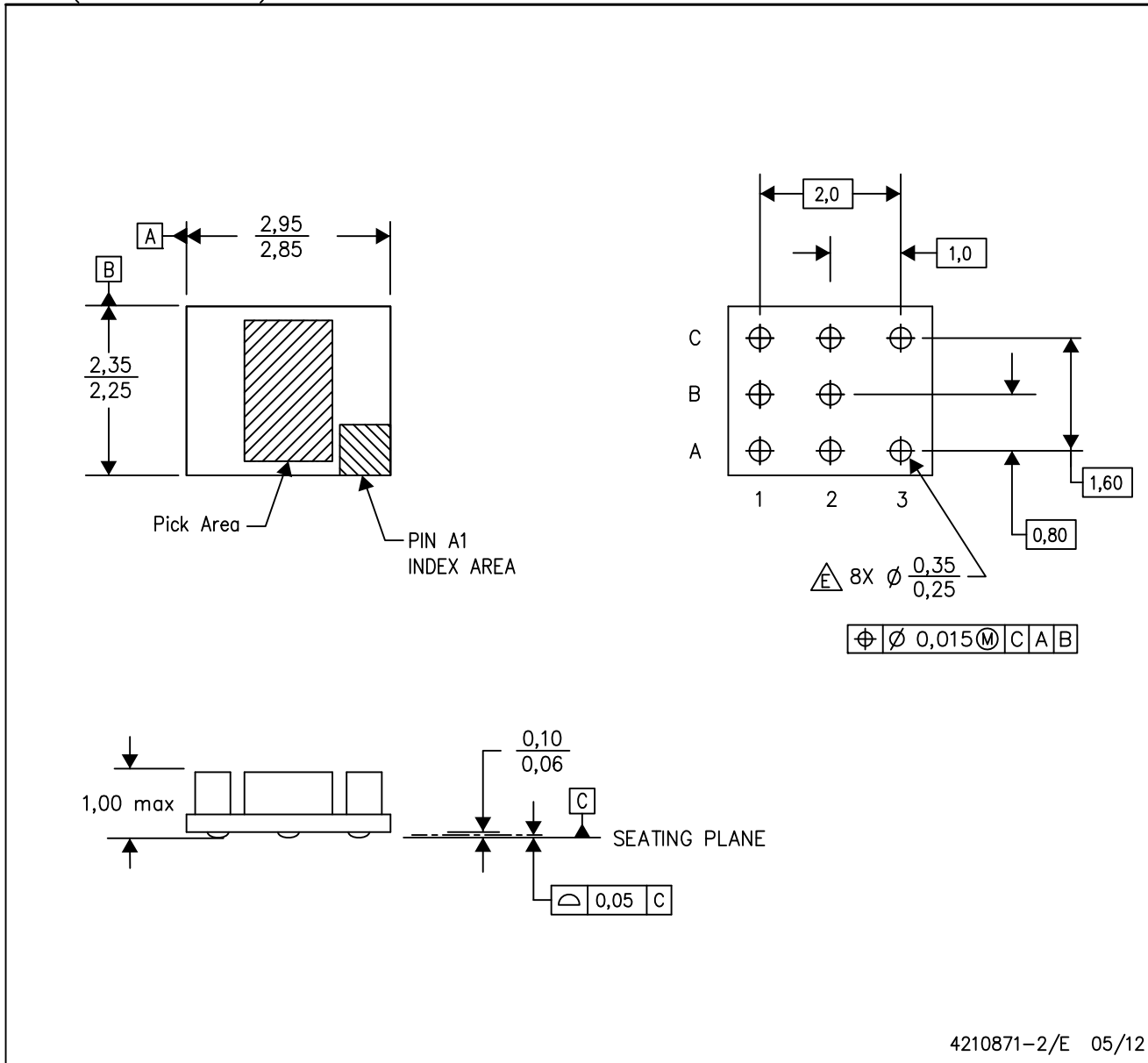


TPS62670SiP, TPS62690SiP, TPS82671SiP, TPS82675SiP

SIP (R-uSiP-N8)

MicroSiP™



4210871-2/E 05/12

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. MicroSiP™ package configuration - Micro System in Package.
 - D. Reference Product Data Sheet for array population.
3 x 3 matrix pattern is shown for illustration only.
 - △. This package contains Pb-free balls.

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